

FLYOVER® TECHNOLOGY

samtec.com/flyover

FLYOVER® TECHNOLOGY

THE PROBLEM PCB REACH AT NEXT GEN SPEEDS

FLY OVER

As bandwidth requirements rapidly increase, effectively managing heat and routing signals through lossy PCBs, vias and other components have become complex challenges.

BANDWIDTH VS. TRADITIONAL & HIGH-SPEED MATERIALS

 PAM4
 FR408
 MEGTRON 6
 MICRO TWINAX

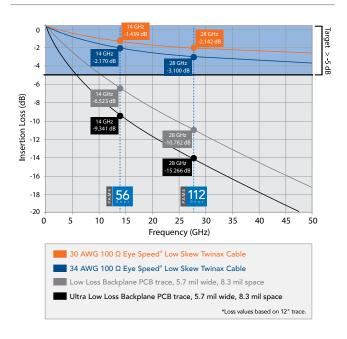
 PAM4
 0.0"
 up to 2"
 36"+

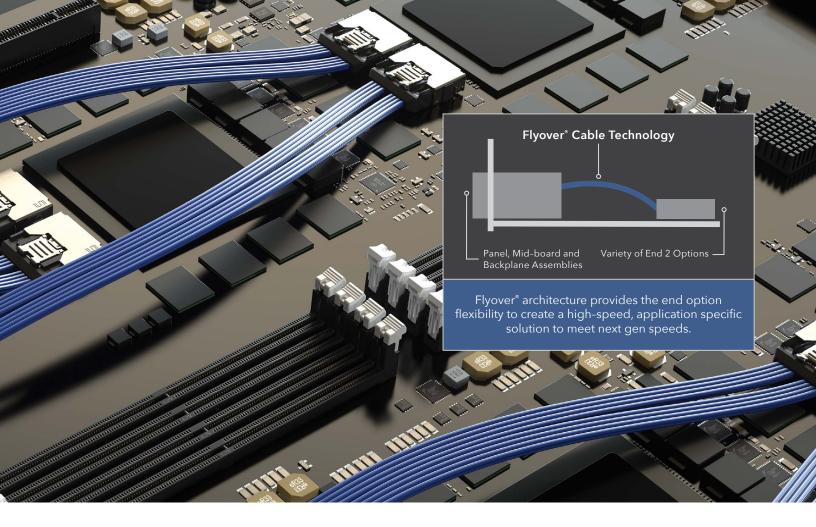
 PAM4
 0.0"
 0.0"
 18"+

(Comparison at -5 dB Insertion Loss Point)

THE SOLUTION SAMTEC FLYOVER® SYSTEMS

Samtec Flyover[®] design breaks the constraints of traditional signaling substrate and hardware offerings, resulting in a cost-effective, high-performance and heat efficient answer to the challenges of 56 Gbps bandwidths and beyond.





EYE SPEED[®] TWINAX CABLE TECHNOLOGY

- Ideal for 28-112+ Gbps applications •
- Tight coupling between signal conductors •
- Ultra low skew twinax < 3.5 ps/meter •
- 40% smaller cross-sectional area (Thinax[™]) .
- In Development: Eye Speed® AIR™ foamed twinax . for significantly improved signal integrity and even lower intra-pair skew

PERFORMANCE & COST ADVANTAGES

- 28-56 Gbps NRZ & Beyond
- Simplified Board Layout •
- Fewer PCB Layers •
- Less Expensive PCB Materials •
- Eliminate Expensive Re-timers

SUPPORT

Fully integrated technology teams provide support to enable full system optimization from Silicon-to-Silicon[™], including Samtec's High-Speed Cable Plants.

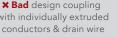


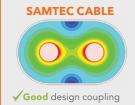
56

56



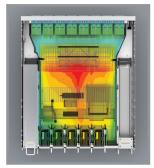
INDUSTRY CABLE





with Samtec's co-extruded ultra low skew twinax

THERMAL IMPROVEMENT

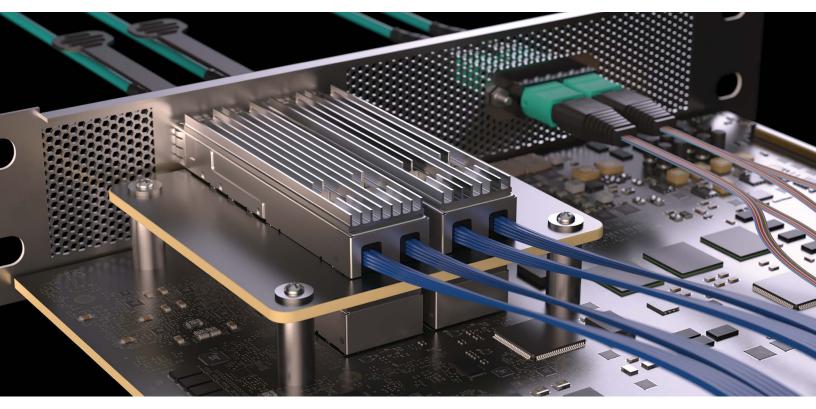




Standard Network Switch VS. Samtec Flyover[®] Technology

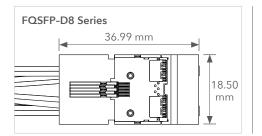
FLYOVER® PANEL ASSEMBLIES

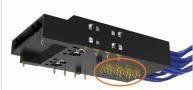




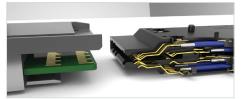
FLYOVER® QSFP SYSTEMS

- Up to 800 Gbps PAM4 aggregate data rate (112 Gbps PAM4 per channel)
- 4 channels (x4 bidirectional, 8 differential pairs) or 8 channels (x8 bidirectional, 16 differential pairs)
- Double density versions feature belly-to-belly mating for maximum density (FQSFP-DD, FQSFP-D8)
- Multiple heat sink options for optimal dissipation
- Variety of end 2 options including AcceleRate[®], NovaRay[®], Si-Fly[™], FireFly[™] and ExaMAX[®]
- Evaluation Kits available, visit samtec.com/kits
- Additional front panel ports in development: Flyover[®] SFP112, Flyover[®] OSFP 112 Gbps PAM4





Sideband signals are routed through press-fit contacts for increased airflow



FQSFP-D8

High-speed contacts directly soldered to Eye Speed® ultra low skew twinax

FLYOVER[®]

NOVARAY® I/O EXTREME PERFORMANCE SYSTEM

- Up to 3,584 Gbps PAM4 aggregate data from the IC package to the panel and beyond
- No heat sinks required for panel space savings
- 16 and 32 differential pair configurations •
- Accommodates PCIe[®] x4 or x8 plus sidebands •
- 28 or 34 AWG (external) and 34 AWG (internal) ultra low skew twinax; single-ended coax option also available
- Cable-to-cable bulkhead panel connection using Flyover® cable technology .

TARGETED CONFIGURATIONS

x8 (16 Pair + PCIe® Sidebands)

102.43 mm

• Multiple end 2 high-speed connector options including AcceleRate®, NovaRay® and Si-Fly™

PAM4 8 Pair (in development) 896 Gbps 16 Pair 1792 Gbps 32 Pair 3584 Gbps x4 (8 Pair + PCIe® Sidebands) 512 Gbps EXPRESS

12.75 mm

NovaRay® I/O in a rugged 38999 shell & salt fog resistant to 48 hours (NVA3E/NVA3P)

PCI-SIG [®] , PCI Express [®] and the PCIe [®]	design marks are registered trademarks and/or service marks of PCI-SIG

ExaMAX® I/O SHIELDED CABLE SYSTEM

- Fully shielded external cable and cage for EMI protection
- Rugged pull latch for mating/unmating
- Cage designed for use with ExaMAX[®] right-angle board • connector (EBTM-RA)
- 30 and 34 AWG ultra low skew twinax
- 24 to 72 pairs (4 and 6 pairs; 6, 8, 10 and 12 columns) .
- Roadmap: cable-to-cable bulkhead panel connection for • increased performance to 112 Gbps PAM4

EBCE/EBTC

PAM4

56







AGGREGATE

DATA RATE

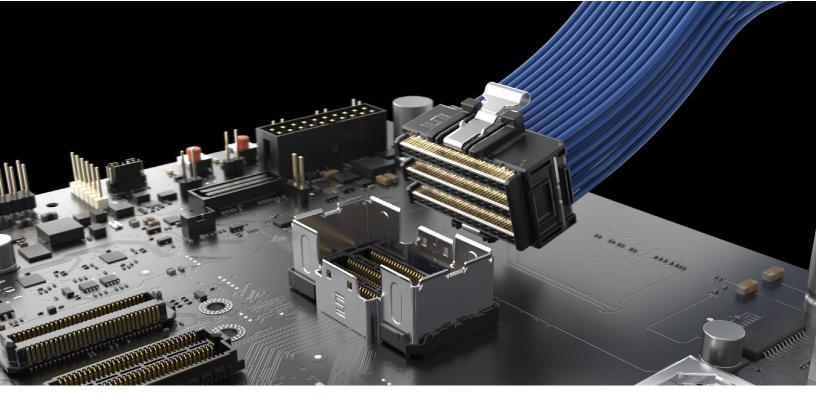
1024 Gbps

NVACE Series (4 Row)

NVACP/NVACE/NVC

FLYOVER® MID-BOARD ASSEMBLIES





NOVARAY[®] EXTREME HIGH-SPEED, HIGH-DENSITY CABLE

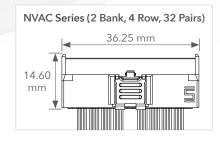
- Industry leading aggregate data rate density 2x the data rate in 60% of the space
- Proprietary pin to ground configuration enables extremely low crosstalk (beyond 40 GHz) and very tight impedance control
- Two reliable points of contact guaranteed
- BGA attach for density and optimized trace breakout region
- Evaluation Kit available, visit samtec.com/kits
- Eye Speed[®] Thinax[™] ultra-performance twinax cable version in development







NVAC/NVAM-CT

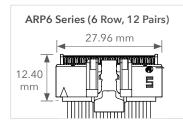


AGGREGATE DATA RATE (NRZ)								
448 Gbps	672 Gbps	896 Gbps		1344 Gbps	1792 Gbps	4032 Gbps*		
	1 Bank			2 Bank		3 Bank*		
2 Row	3 Row	4 Row	2 Row	3 Row	4 Row	6 Row*		
8 Pairs	12 Pairs	16 Pairs		24 Pairs	32 Pairs	72 Pairs*		

*In development

ACCELERATE® HP EXTREME DENSITY SYSTEM

- Industry's highest density 112 Gbps PAM4 cable-to-board system •
- Supports today's 256-channel chip and tomorrow's 512-channel chip
- Staggered row-to-row spacing of 2.2 mm x 2.4 mm allows adequate • routing lanes for optimized traces; 0.635 mm contact pitch
- 32 to 72 differential pairs; up to 96 pairs in development •
- Eye Speed® 34 AWG ultra low skew twinax cable •
- BGA solder ball attach for simplified board processing •
- Right-angle shielded mating connector • in development (APF6-RA)
- Eye Speed® ThinSE[™] 34 AWG single-ended micro • coax version in development with 12 or 18 coax per row





ARP6/APF6-L

ACCELERATF[®]*HP*

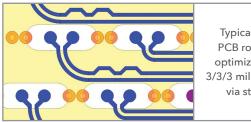


Locking available for maximum density

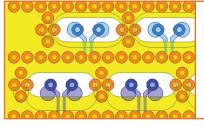
ART6/ATF6

ACCELERATE® HP GEN 2 ON-PACKAGE SYSTEM

- Samtec is the first to achieve a direct-to-chip package solution with the industry's highest density 112 Gbps PAM4 interconnect
- Double the density in the same Gen 1 footprint; up to 144 differential pairs •
- 182 differential pairs per square inch •
- Staggered row-to-row spacing; 0.635 mm contact pitch •
- Eye Speed® Thinax™ ultra performance twinax cable
- Vertical cable application provides the highest footprint density •
- 2-piece system for high reliability and thermal performance required for co-packaged solutions
- Roadmap: Eye Speed[®] ThinSE[™] single-ended micro coax cable assembly, • and mixed wafer technology with ThinSE[™] single-ended micro coax and Thinax[™] ultra-performance twinax cable



Typical HDI PCB routing optimized for 3/3/3 mil with no via stubs



35 mm x 35 mm footprint

holds two 72 differential pair connectors (144 total pins)

> AcceleRate[®] HP routing in HDI PCB with excellent crosstalk isolation and unimpeded routing channels

ACCELERATE[®]HP

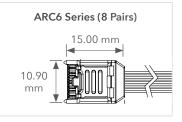
Flyover[®] Mid-Board Assemblies



ACCELERATE® SLIM, DIRECT ATTACH SYSTEM

- Slimmest cable assembly in the industry 7.6 mm width
- 8, 16 and 24 differential pair configurations in a highdensity 2-row design; 72 pairs in development
- Supports 64 Gbps PAM4 (32 Gbps NRZ) applications
- PCIe[®] 6.0 capable
- Contacts directly soldered to the twinax improves signal integrity by eliminating the transition board and its variability
- Eye Speed® 34 AWG ultra low skew twinax cable
- Rugged metal latching and shielding
- "Reversed Polarity" pinout option for reduced Far-End Crosstalk
- Evaluation Kits available, visit samtec.com/kits

Right-angle board mate available (ARF6-RA)



ACCELERATE[®] MINI EXTREME PERFORMANCE SYSTEM

- Eye Speed® 34 AWG Thinax™ ultra performance twinax cable
- One or two differential pairs
- Vertical and right-angle mating board connector
- Design flexibility as an End 2 option for Flyover® assemblies
- Friction retention latching and alignment pins

ACCELERATE[®] mini

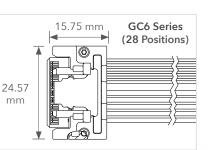


ACCELERATE[®]

ARC6/ARF6

GENERATE[™] HIGH-SPEED EDGE CARD SYSTEM

- Compatible with SFF-TA-1002 (1C, 2C, 4C & 4C+)
- Supports 64 Gbps PAM4 (32 Gbps NRZ) applications
- PCIe[®] 6.0 capable
- Edge Rate[®] contacts optimized for signal integrity performance
- Vertical or right-angle cable launch
- Mates with Generate[™]
 0.60 mm pitch high-speed edge card socket (HSEC6)
- Rugged metal latching system





PAM4

GC6/HSEC6



SI-FLY[™] LOW PROFILE CABLE SYSTEM

- Up to 16 pairs in an extremely low 4 mm profile for placement adjacent to the IC package, under heat sinks or other cooling hardware
- 112 Gbps PAM4 per lane enabling 25.6 TB aggregate with a path to 51.2 TB
- High-density 8 or 16 pairs for routing 4 or 8 channels
- Eye Speed® 34 AWG ultra low skew twinax cable
- 8.4 mm minimum height required for mating
- Evaluation Kit available, visit samtec.com/kits



SI-FLY[™] HIGH-DENSITY ON-PACKAGE SYSTEM

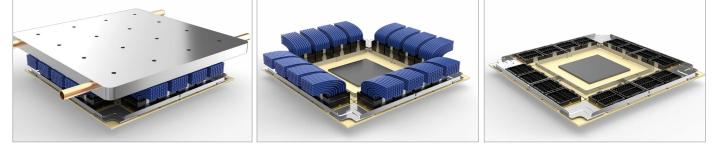
- Vertically launched cables for the highest density package
- 64 pairs in an incredibly small 14 mm x 14 mm footprint
- 245 differential pairs per square inch
- 0.53 mm (Signal-Ground) and 0.40 mm (Signal-Signal) contact pitch;
 1.25 mm row-to-row pitch
- Designed for High Density Interconnect (HDI) and package substrates
- Eye Speed® AIR™ foamed twinax cable for significantly improved signal integrity and even lower intra-pair skew





HPC/HPI

CPC/CPI



Ultra-high density solution for co-packaged applications.

FLYOVER® BACKPLANE CABLES





NOVARAY[®] MICRO RUGGED BACKPLANE SYSTEM

- True 112 Gbps PAM4 signal integrity with Flyover® support
- Cable-to-board, cable-to-cable, board-to-board
- Configurable signal banks for design flexibility
- Offset footprint for optimal signal integrity performance
- Reliable two points of contact for stub free mating
- Large continuous ground blades between and surrounding the differential pairs eliminate resonances
- Optional guidance and keying for blind mate





Precision Insert Molded Contact System

Solder Charge Termination for Higher Densities

Supports Blind Mate Applications

NVCF/NVBF/ NVBM-RA

NOVARAY

Ultra High-Density; up to 128 DPs in a Single Connector

Single-Ended or Differential Pair Wafers

ExaMAX® HIGH-SPEED BACKPLANE SYSTEM

- Cable-to-cable, cable-to-board, mid-board and panel applications
- Highly customizable with modular flexibility
- Reduced costs due to lower PCB layer counts
- 4 and 6 pairs; 4-16 columns

EBCF Series

(36 Pairs Total)

14.60 mm

- Integrated guidance and keying options
- Multiple end 2 options available
- Evaluation Kit available, visit samtec.com/kits

23.68 mm

• Eye Speed® Thinax™ ultra performance twinax cable version in development

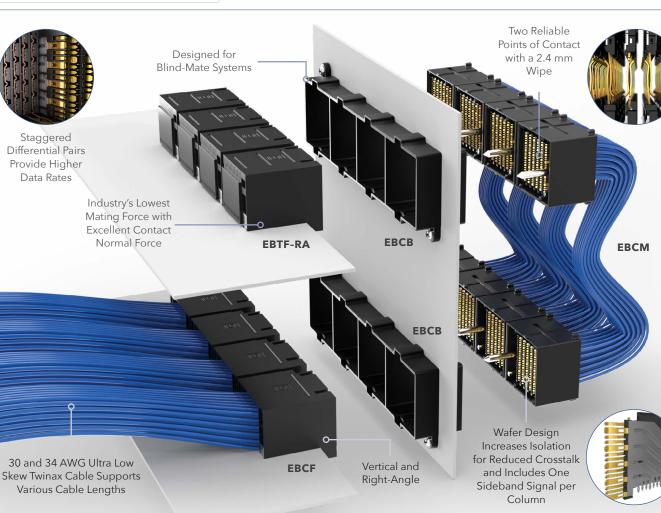


Roadmap: 8 Pairs for Greater Design Flexibility



EBCF/EBDM-RA

Cable-to-DMO (Direct Mate Orthogonal)





also available

ExaMAX[®]

EYE SPEED[®] CABLE TECHNOLOGY



ULTRA LOW SKEW TWINAX CABLE

Samtec's proprietary Eye Speed[®] co-extruded twinax cable technology eliminates the performance limitations and inconsistencies of individually extruded dielectric twinax cabling, improving signal integrity, bandwidth and reach for high-performance system architectures.

- Tight coupling between signal conductors
- Improved bandwidth (28-112+ Gbps) and reach
- Improved signal integrity and eye pattern opening
- Ultra low skew (< 3.5 ps/meter) over extended lengths
- Supports Samtec Flyover® technology

Micro Cellular Dielectric Extrusion

- Critical dimensions measured at every dielectric spool
- Inline laser and CAPAC devices for capacitance monitoring and diameter control
- In-process stats summary sheet for Cpk acceptance

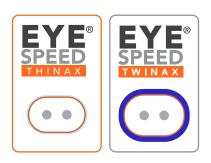


Eye Speed [®] Ultra Low Skew Twinax		28 AWG	30 AWG	32 AWG	34 AWG	36 AWG	
Nominal Performance Specifications						42.	
14 GHz	0.25 m	IL (dB)	-1.0	-1.2	-1.5	-1.8	-2.2
(28G NRZ/ 56G PAM4) 28 GHz (56G NRZ/ 112G PAM4)	1.00 m		-4.1	-4.7	-5.9	-7.5	-8.9
	0.25 m		-1.5	-1.8	-2.2	-2.7	-3.2
	1.00 m		-6.1	-7.1	-8.7	-10.9	-13.0
Density/Flexibility		Good	Good	Better	Best	Best	

* Eye Speed* Ultra Low Skew Twinax Cable is available in engineered impedance configurations of 85 Ω, 92 Ω and 100 Ω.

THINAX[™] ULTRA PERFORMANCE TWINAX CABLE

- 40% smaller cross-sectional area
- 112 Gbps PAM4 performance
- Taped jacket miniaturizes the cable to match smaller, more dense connectors
- Allows for a smaller pitch within a row
- Achieving a smaller row-to-row pitch is dependent upon stack-up and BOR; customizable per application needs
- In Development: Eye Speed[®] AIR[™] foamed twinax for significantly improved signal integrity and even lower intra-pair skew



DIRECT ATTACH CABLE

- High-density contacts directly soldered to the Eye Speed® ultra low skew twinax cable
- Improved signal integrity by eliminating the transition board and its variability
- Achieves tighter tolerances



MICRO COAX CABLE

- Foaming introduces air voids for signal to travel faster
- Solid extrusion of foamed dielectric provides a constant and more durable construction
- Lighter weight and smaller size with higher bandwidth capabilities at longer lengths
- 26 38 AWG cable available
- Choice of signal conductor, shield and FEP dielectric to meet performance and cost specifications

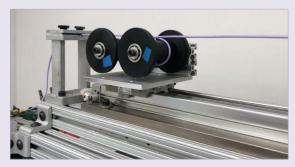


DYNAMIC TESTING

Samtec Eye Speed^{*} **Ultra Low Skew Twinax** cable underwent Dynamic Insertion and Return Loss testing, proving the cable to be rugged with stable electrical performance after 250 flex/bend cycles.

This arduous flex and bend test determined that the performance of Samtec Eye Speed[®] ultra low skew twinax is essentially indistinguishable from the original raw, unbent cable.

Ultra low skew twinax provides the lowest insertion loss in the industry, controlled performance across temperature, and robust insertion loss in any assembly and operation environment. Contact **HDR@samtec.com** for higher cycle results.



Six feet of ultra low skew twinax cable on mandrels was coiled/uncoiled moving back and forth on a slide at a rate of 20-25 cycles per minute.

CABLE MANAGEMENT

- Samtec works with system architects in the early stages to optimize the architecture for cable management while keeping signal integrity and thermals in mind
- Complimentary service using mockups with accurate cable lengths
- Minimize number of SKUs within one system
- Minimize pressure drop



HIGH-SPEED CABLE DESIGN FLEXIBILITY







ANY break-out configuration



... to create a solution for **any specific application.**

HDR@samtec.com



Visit **samtec.com/custom** for additional information.

WILLINGNESS, SUPPORT & EXPERTISE

Industry-Leading Customer Service

- Quotes and samples in 24 hours
- Prototype and processing assistance
- Dedicated Application Specific Product engineers and technicians

Flexible, In-House Manufacturing

- Global Operations, including multiple cable fabrication & assembly facilities
- Quick-turn samples and prototypes
- Custom & modified product support

Signal Integrity Expertise

- Industry-leading engineering support for high-performance system design
- Full system optimization assistance, including simulation, testing, analysis and evaluation



CUSTOMS & EXPRESS MODIFICATIONS

Samtec is able to support completely new and/or custom designs, as well as common simple modifications to cable assemblies and board-to-board products - often with low or no NRE charges, short lead times, quick-turn samples, and low or no MOQ's. Capabilities include:

- Contacts
- Bodies
- Stamping
- Ruggedizing features
- Wiring
- Molding
- Plating
- Polarization

- Packaging
- Labeling
- Ink printing
- Shielding modifications

 Ouble-ended micro coas cable assembly with two connectors

 Ouble-ended micro coas cable assembly with two connectors

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